



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

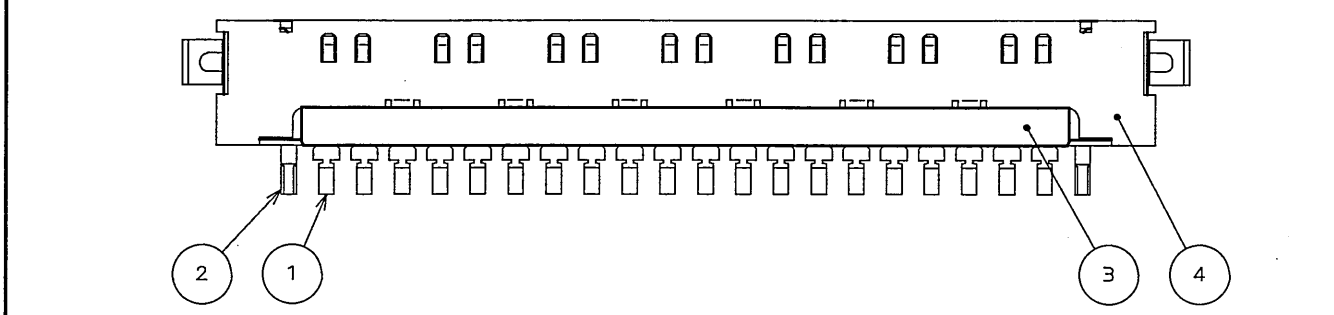
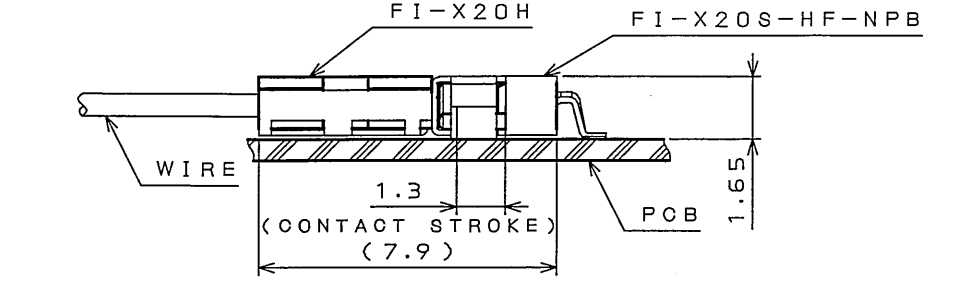
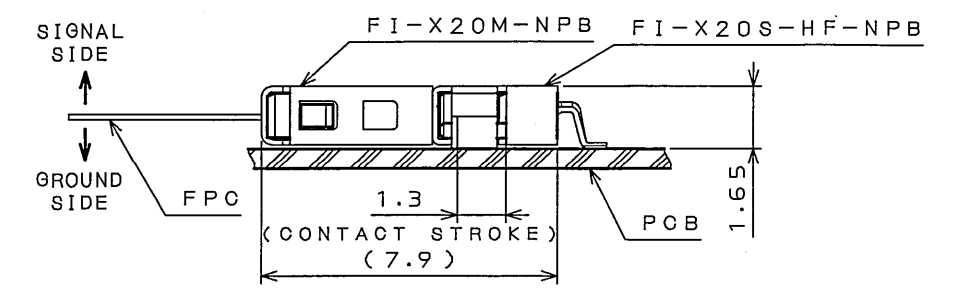
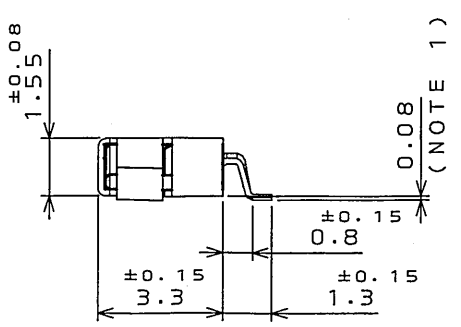
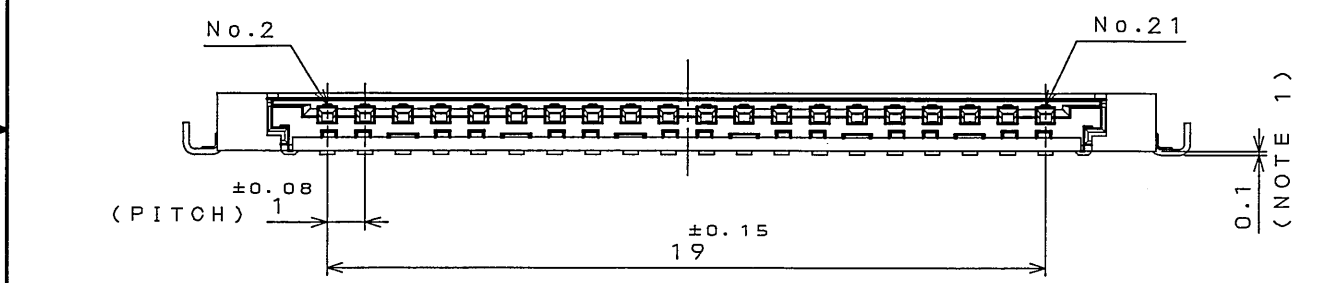
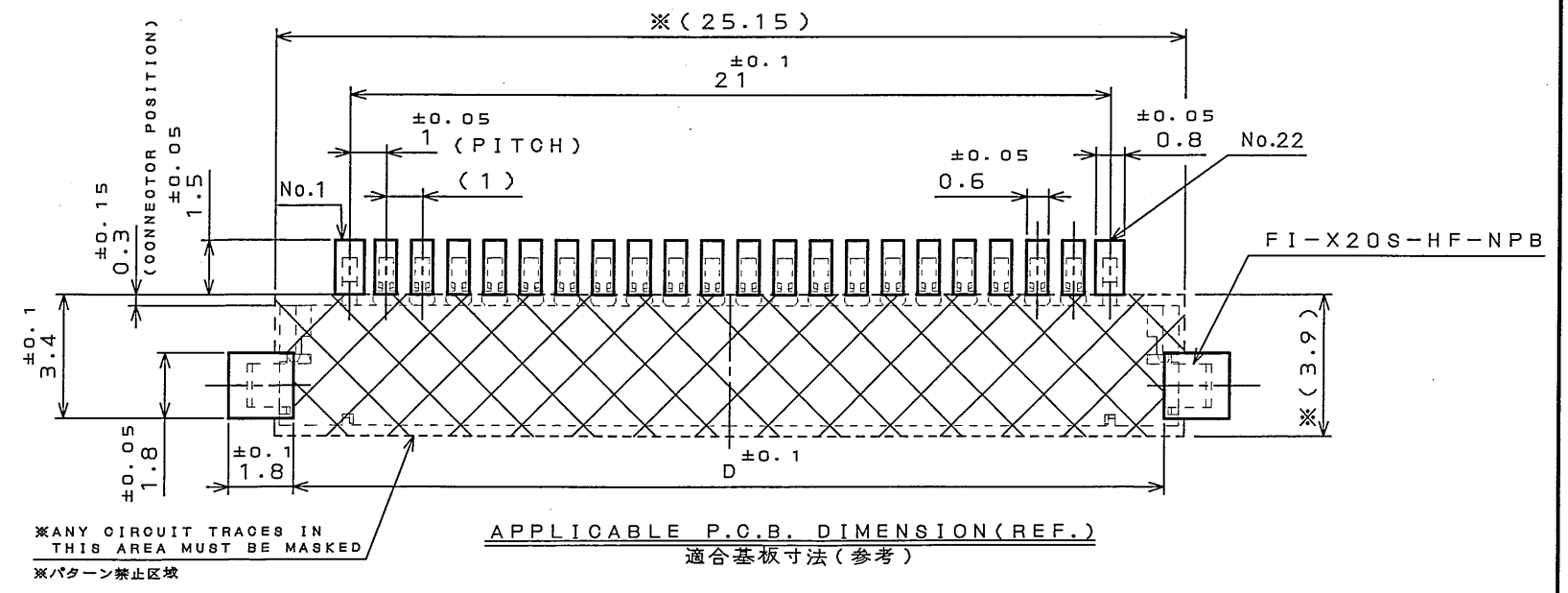
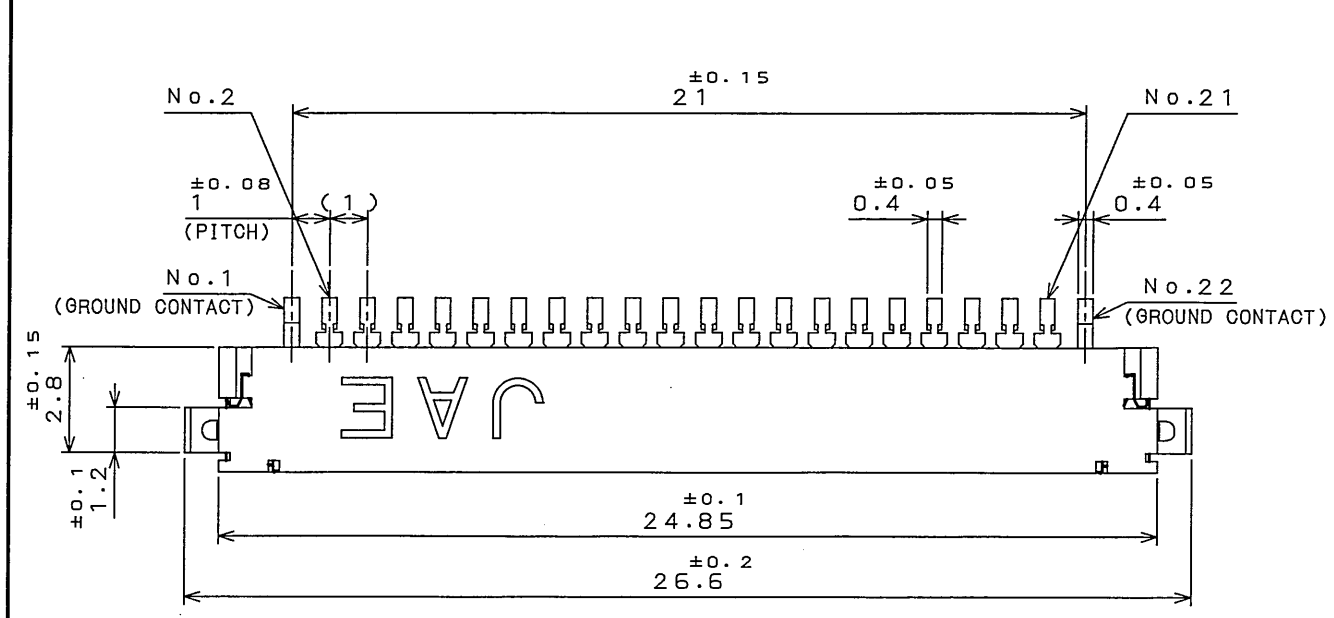
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



6E6001PS
('ON 0N1MAYD) 台 号 图 号

| 版数 REV. | 年月日 DATE | DCN NO. | 変更内容 DESCRIPTION | 製図 DR. | 担当 CHK. | 査閲 APPD. | 承認 APPD. |
|---------|-------------|---------|------------------|--------|----------|----------|----------|
| 2 | 10.Jun.2004 | 055279 | CORRECT AN ERROR | | T.YAMAJI | M.Suzuki | Y.Morino |

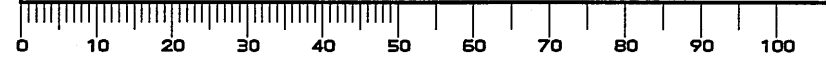


| 符号 NO. | 名称 DESCRIPTION | 個数 QTY. | 材料 MATERIAL | 仕上 FINISH | 備考 REMARKS |
|--------|----------------|---------|------------------------|-------------------------------|--|
| 4 | SHELL | 1 | COPPER ALLOY | TIN PLATING | |
| 3 | INSULATOR | 1 | HEAT RESISTING PLASTIC | | UL94 V-0 BEIGE |
| 2 | GROUND PLATE | 1 | COPPER ALLOY | TIN PLATING | |
| 1 | CONTACT | 20 | COPPER ALLOY | GOLD(0.1μmMIN) OVER NICKEL | △ TERMINAL AREA: TIN-COPPER OVER NICKEL |

NOTE 1. COPLANARITY BETWEEN TERMINAL AND HOLD DOWN OF SHELL SHOULD BE 0.08mm MAX.
2. TERMINALS NO.1 AND 22 ARE APPROPRIATE FOR GROUND CONTACTS.
注1. 端子及び、シエルのホールドダウンの相互のバラツキは0.08以内である。
2. 端子No. 1, 22はグラウンド専用コンタクトとする。

| | | | | |
|---------------------|------------------------------------|--|-----------------------|---|
| 仕様書 (SPECIFICATION) | 第1版 (ORIGINAL DATE) 23.Mar.2004 | 尺度 (SCALE) 5:1 | シリーズ (SERIES) FI-X | 日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. 図面番号 (DRAWING NO.) SJ100939 |
| 製図 DR. | H.YOKOO | 名称 (TITLE) FI-X20S-HF-NPB (PCB SIDE) | | |
| 担当 CHK. | T.YAMAJI | 重量 (WEIGHT) | | |
| 査閲 APPD. | M.SUZUKI | | | |
| 承認 APPD. | T.MORINO | | | 版数 (REV.) 2 |

DOF-C-212E(03.08)



LEAD FREE この製品は鉛フリー品です